

EPS Malaysia Webinar Series 2021

Advanced Packaging for Autonomous Driving

Great business opportunities in many industries are made available due to the advancement in autonomous driving technology, driven by automotive megatrends. Architecting the autonomous car requires comprehensive system solutions with safety and security built in. Car electronics packaging are changing to meet the higher functional requirements. New package types emerges as a result of greater innovation. The future of packaging is definitely more exciting!

Dr Eu Poh Leng has been with Motorola/Freescale/NXP Semiconductors Malaysia for 24 years and has been very actively involved in the development and introduction of new technology and new product in internal and external factories. She has published 65 technical papers and 4 journals externally, and owns 23 filed and 11 issued patents



Dr. Eu Poh Leng

**Director,
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JOIN US FOR THIS UPCOMING WEBINAR

Date: 27 July 2021 (Tuesday)
Time: 10.00-11.00 a.m. (M'sia Time, GMT +8:00)
Platform: CISCO WebEx

REGISTER NOW

(Click the link for registration)

**E-certificates will be provided to all participant*

- The current automotive market for the IC (integrated circuit) packaging industry has grown significantly due to the increasing need for automation and higher performance in vehicles.
- These changes in the automotive market will enable cars to be more reliable and intelligent.

JOIN US! It is **FREE!**

Enroll yourself and join us in this exciting webinar. See you there!